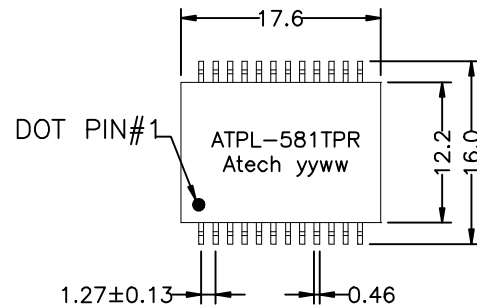
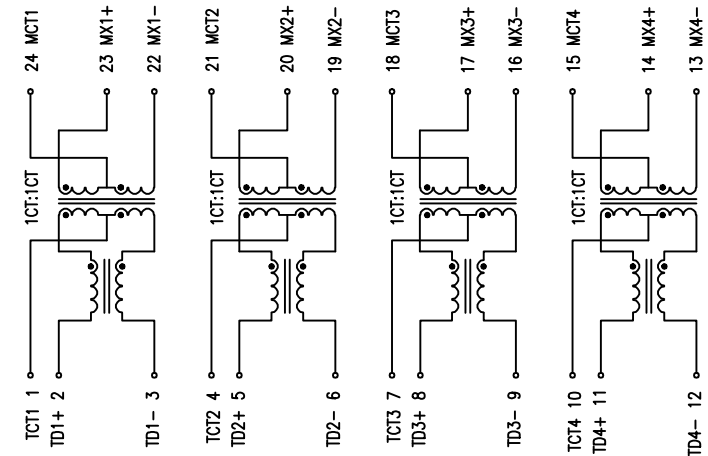


SUGGESTED PAD LAYOUT

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE ±0.25mm

CABLE SIDE



CHIP SIDE

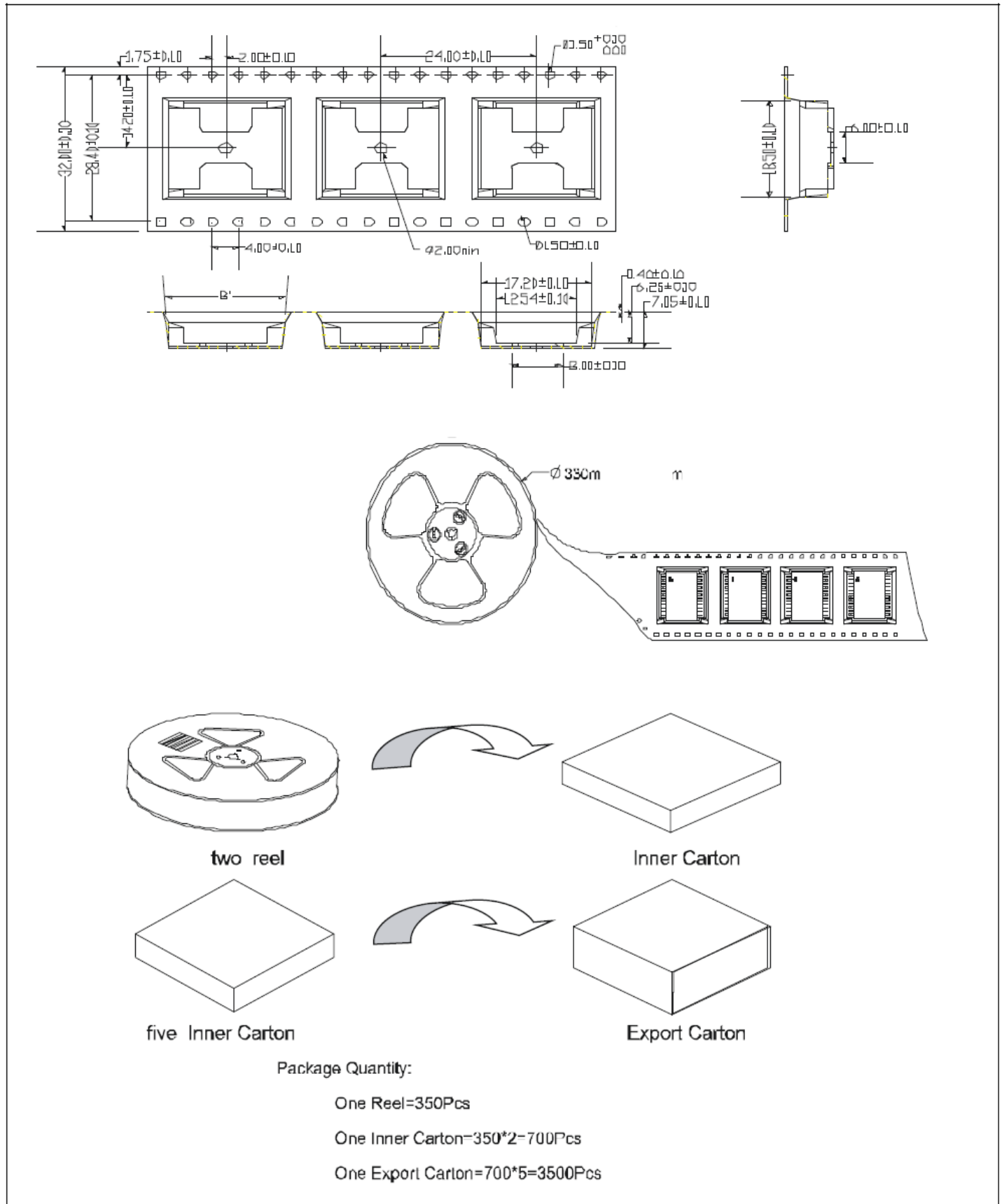
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS@25°C

1. OCL : (@100kHz, 0.1V) : 150uH MIN. 18mA DC BIAS
2. DCR : 1.0Ω MAX.
3. TURNS RATIO : 1CT : 1CT ±5%
4. INSERTION LOSS : (@1-100MHz) : -1.0dB MAX.
(@100-250MHz) : -2.0dB MAX.
5. RETURN LOSS : (@1≤f≤40MHz) : -16dB MIN.
(@40<f≤250MHz, where f is in MHz) : -16+10 log (f/40)dB MIN.
6. CROSS TALK : (@1-125MHz) : -30dB MIN.
(@125-250MHz) : -25dB MIN.
7. COMMON MODE REJECTION : (@1-125MHz) : -30dB MIN.
(@125-250MHz) : -25dB MIN.
8. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
9. COMPLY WITH IEEE802.3bz & 802.3bt
10. DESIGNED TO SUPPORT APPLICATIONS UP TO 1200mA PER CENTER TAP
11. OPERATING TEMPERATURE : -40°C to +85°C
12. STORAGE TEMPERATURE : -40°C to +125°C

								TITLE 2.5G POE TRANSFORMER	
								DWG. NO. ATPL-581TPR	
	RELEASE	05/11/2023	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 of 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	DRAW	
REVISIONS						05/11/23			SHIRLEY

3. Package :



Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to T _p)	3°C/second max	3°C/second max
Preheat Temperature Min (T _{sm}) Temperature Min (T _{sm}) Time (T _{sm} to T _{sm}) (t _s)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T _L) Time (t _L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T _p)	225°C	260°C
Time within 5°C of actual Peak Temperature (T _p) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max